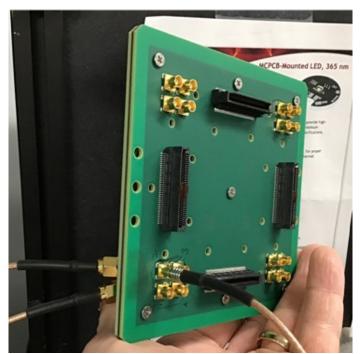
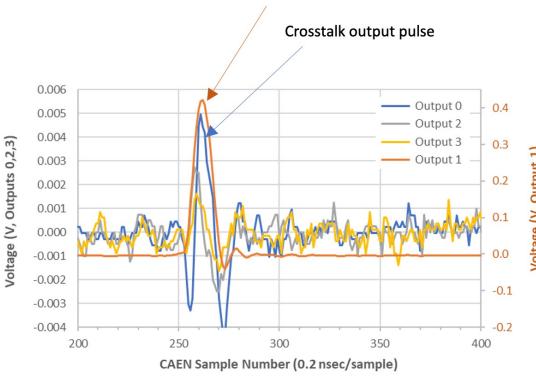
Interposer interface cross-check at Incom



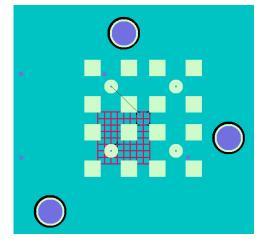




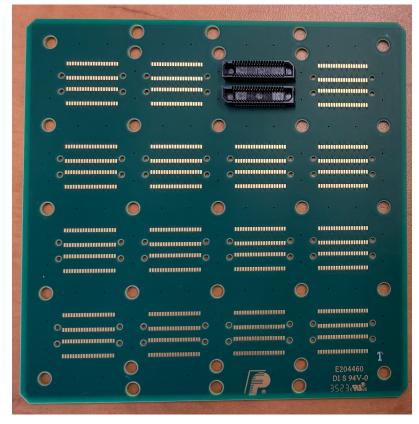
Expected output pulse

Two boards bolted together back-to-back via a stock Samtec interposer

- > A 2x2 pad area on an older board was used for this exercise (Y05a)
- > Observations:
 - ➤ Signal transmission via "5mm trace -> interposer -> 5mm trace" (and a pair of RG-316 cables) ~98%
 - Cross-talk on a neighboring pad <2%

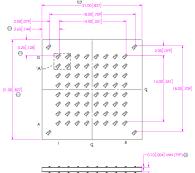


A dummy HRPPD readout board Y05f



top side (32x Samtec ERF8 connectors)

bottom side (matches HRPPD rear side)

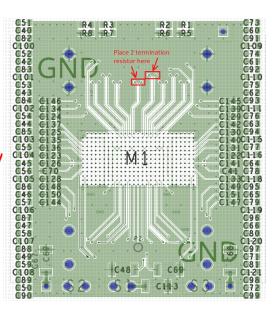


- > Assembly order for 5 boards is being placed
- Connectivity for any of the sixteen 8x8 pad fields (got a quote already):
 - ➤ A set of [2x Samtec ERM8 -> MMCX] adapters, 32ch (4x8) connected at a time
 - ➤ A set of ERM8-based grounding caps for all other 8x8 fields

Test stand at Brookhaven



- > A small HGCROC3 installation at BNL
 - > Essentially a Linux-based copy of Oak Ridge setup
 - KCU105 FPGA kit provided by John Kuczewski (BNL)
 - Carrier board by Norbert Novitzky (ORNL)
 - ➤ HGCROC3 mezzanine board by Damien Thienpont (IN2P3)
 - > FPGA firmware by Miklos Zeller (Debrecen)
 - Should be sufficient for writing an RCDAQ driver
 - First via USB, then gigabit ethernet
 - Not really functional as of yet
 - > Issues with on-board termination
 - A fix by Miklos was a partial success story
 - ➤ Where do we go from here:
 - AK meets with Norbert in the US?
 - ➤ AK comes to Orsay mid October?



A situation with FY24 funding

- > ASIC interface development was originally split between two R&D proposals:
 - > eRD110 (photosensors): pilot version and a single full set (\$10k)
 - eRD114 (pfRICH prototype): four more sets (\$25k)

This did not really fly

- Money gets dispatched via BNL (easy way)
- Present status: everything is packed into eRD114 proposal

Five 3D printed HRPPD enclosures	\$2k
120 HGCROC3 ASIC chips	\$12k
Five readout backplane assemblies	\$16k
Two KCU105 evaluation kits	\$8k
Beam test travel	\$35k
Total	\$73k

This does not seem to fly either

- ➤ Next iteration: a consolidated *PED* funding request for the same grand total of ~\$35k?
 - Money gets dispatched via JLAB (a "less easy" way)

Timeline-wise boundary conditions

- > pfRICH beam test in June 2024 (all five ASIC / FPGA board sets + DAQ interface)
 - > Obviously, all this needs to be available several months earlier
 - Call it March 2024 the latest?
- > HRPPD routine evaluation in the lab (first BNL, then Yale, then INFN, Argonne & Glasgow)
 - ➤ If it starts past June 2024, this is probably fine